ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

01 Oct 2007

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #16055

TITLE: Capacity Expansion for Devices Fabricated at XFAB Wafer Foundries

PROPOSED FIRST SHIP DATE: 01 Feb 2008

AFFECTED CHANGE CATEGORY: Subcontractor Fab Site

AFFECTED PRODUCT DIVISION: Digital Consumer Group, Computing Products Group, Standard Products Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Todd Manes <todd.manes@onsemi.com>

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce a general capacity expansion qualification for devices fabricated at the XFAB wafer foundries. XFAB is a sub-contract wafer fab company currently providing wafer manufacturing services to ON Semiconductor at facilities in Erfurt, Germany and Lubbock, TX (USA).

This is an Initial PCN announcing ON Semiconductor's intention to expand manufacturing capacity and improve manufacturing flexibility by qualifying products at one or more of the XFAB facilities, including a third XFAB facility located in Kuching, Malaysia. All XFAB facilities are certified ISO9001:2000 compliant. XFAB offers the same process technology in all three fab locations; therefore, no die design changes are anticipated. Device performance will be the same among the qualified facilities for each device family. All devices will continue to be assembled and tested in existing, qualified locations. No changes to packaging will occur as a result of this foundry expansion qualification.

Initial Product/Process Change Notification #16055

QUALIFICATION PLAN:

The capacity expansion will be focused on qualifying devices for production at the Lubbock, Texas and/or Kuching, Malaysia facilities. Qualification activity will be performed on individual devices or groups of devices as necessary to ensure maximum capacity and manufacturing flexibility. Specific plans and qualification results for each device or device family will be announced via individual Final PCN's as those qualifications are achieved.

Generally, the Erfurt, Germany and Lubbock, Texas facilities are qualified and running production in significant volume. Qualifications between these two facilities will utilize existing reliability data where appropriate. Qualifications at the Kuching, Malaysia facility will include a full set of reliability testing for the initial devices to be qualified there. When sufficient qualification data has been gathered, future product qualifications at the Kuching facility will reuse qualification data as appropriate.

Initial Product/Process Change Notification #16055

AFFECTED DEVICE LIST:

PART
NCN6001DTBR2
NCN6001DTBR2G
NCN6004AFTBR2
NCN6004AFTBR2G
NCP2809ADMR2G
NCP2809BDMR2G
NCP2820FCT1G
NCP2820FCT2G
NCP2820MUTBG
NCP2890AFCT2G
NCP2890DMR2G
NCP4894DMR2G
NCP4894FCT1G
NCP4894MNR2G
NB3L553DG
NB3L553MNR4G
NB3L553MNR4G
NB3N2304NZDTG
NB3N2304NZDTR2G
NB3N2304NZMNR4G
NB3N502DG
NB3N502DR2G
NB3N551DG
NB3N551DR2G
NCN4555MNG
NCN4555MNR2G
NCN4557MTG
NCN4557MTR2G
NCN6804MNR2G
NCP2809ADMR2G
NCP2821FCT1G
NCP2892AFCT2G
NCP2892BFCT2G
NCP2990FCT2G
NCP5005SNT1G
NCP5006SNT1G
NCP5007SNT1G
NCP5030MTTXG
NCP5351DG
NCP5351DR2G
NCP5351MNR2G
NCP5602MUTBG
NCP5603MNR2G
NCP5604AMTR2G
NCP5604BMTR2G
NCP5608MTR2G
NCP5612MUTBG
NCP5623MUTBG